

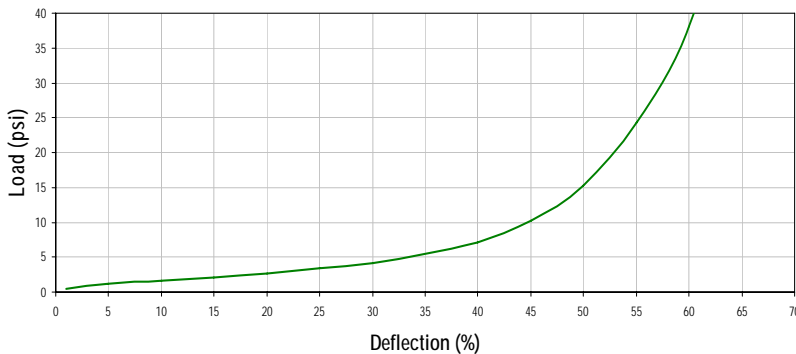
THERM-A-GAP T635, T636 Thermally Conductive Form-in-Place Gap Fillers

DESCRIPTION

THERM-A-GAP™ T635 and T636 are Chomerics' newest developments in form-in-place thermally conductive gap fillers in response to the need to manage ever increasing heat loads. These materials are ideal for applications where gap filling pads overstress component solder joints and leads which can result in catastrophic system failure. Both T635 and T636 are highly conformable, one component, pre-cured silicone gels that can be dispensed to fill large and uneven gaps in electronics assemblies. These viscoelastic pastes are form stable, fully cured silicone materials that require low compressive force to deform during assembly. Because they are pre reacted they require no mixing or cure and have no filler particle settling issues.



T636 Deflection vs. Load



(1" x 1" sample, 0.100" initial thickness)

FEATURES

- Highly conformable at low pressures
- Requires no mixing or curing
- Form stable
- No filler settling issues
- Dispensable for any gap size > 0.010"
- No pot life to produce yield losses

PART NUMBERS:

65-00-T6XX - 0010	10 CC SAMPLE
65-00-T6XX - 0030	30 CC CARTRIDGE
65-00-T6XX - 0180	180 CC CARTRIDGE
65-00-T6XX - 0300	300 CC CARTRIDGE

APPLICATION

T635 and T636 are supplied in plastic syringes and aluminum cartridges. Apply pressure to the rear of the cartridge, dispense the desired amount onto the component and swipe the tip along the component to break the bead of material. Excess material can be wiped up with a rag. Refer to our Applications Note for more detailed application information.

T635 and T636 have also been successfully applied with automated high volume dispensing equipment. Contact Chomerics for details

HANDLING

Dispense the gap filling material onto the component, assemble and secure the heat sink or chassis in place, and the product is ready to ship. No mixing or cure cycles are required. The ease of application of this material is also ideal for rework and field repair. T635 and T636 require no refrigeration, are stored at room temperature and have no filler settling issues.

Typical Properties	T635	T636	Test Method
Color	White	Yellow	Visual
Composition	Boron Nitride Filled Silicone	Boron Nitride Filled Silicone	--
Thermal Conductivity, W/m-K	1.7	2.4	ASTM D5470
Operating Temperature Range, °C	-50 to 150	-50 to 150	--
Deflection, % @ 5 psi Stress	35	35	ASTM C165
Specific Gravity	1.2	1.2	ASTM D792
TGA Weight Loss, % 3 hours, 150°C	0.5	0.4	ASTM D6375
Flow Rate*	10 cc/min	10 cc/min	--
Volume Resistivity, ohm-cm	1 X 10 ¹⁴	1 X 10 ¹⁴	ASTM D257
Shelf Life, months	18	18	--

* 30 cc taper tip syringe, 90 PSI (0.13" orifice)